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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:)
Shinji TAKEDA et al.) Atty. Docket No.: **TM&K0006**
Serial No. 09/785,194)
Filed: February 20, 2001) Group Art Unit: 1755
For: SEMICONDUCTOR DEVICE AND)
PROCESS FOR FABRICATION)
THEREOF) Examiner:
Date: May 4, 2001

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

This is a Supplemental Information Disclosure Statement with regard to the above-identified application. Copies of the document listed in the attached Form PTO/SB/08A are attached.

Document A relates to an insulating adhesive tape. Document B relates to electrically conductive bonding films. Document C relates to a resin-sealed semiconductor device. All of the documents were cited during prosecution of the applicants' parent application, i.e., Serial No. 08/981,702 filed March 31, 1998.

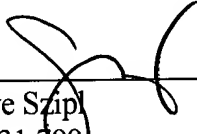
Additionally, the Examiner is advised that the following are related to the above-captioned application: U. S. Patent No. 6,099,678 and U. S. Patent Applications Serial Nos. 09/543,427, 09/616,943, 09/785,436 and 09/785,486.

It is respectfully requested that the attached documents be considered and officially cited, and that a copy of the Form PTO/SB/08A, initialed by the Examiner to indicate that the documents have been considered, be returned to the applicants.

It is believed that the present Information Disclosure Statement complies with the requirements of 37 C.F.R. §§ 1.97-8, but if a fee should be required, authorization is hereby given to deduct from deposit account No. 501281.

Respectfully submitted,

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